

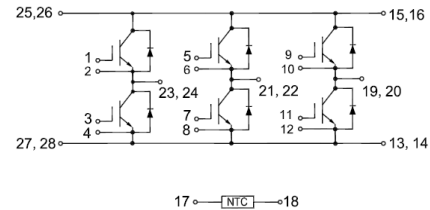


GT40FF120T5H

IGBT Module

Features:

- Field Stop Trench Gate IGBT
- Short Circuit Rated >10μs
- Low Saturation Voltage
- Low Switching Loss
- 100% RBSOA Tested(2×I_c)
- Low Stray Inductance
- Lead Free, Compliant with RoHS Requirement



Applications:

- Industrial Inverters
- Servo Applications

IGBT, Inverter

Maximum Rated Values (T_C=25°C unless otherwise specified)

V _{CES}	Collector-Emitter Blocking Voltage		1200	V
V _{GES}	Gate-Emitter Voltage		±20	V
I _C	Continuous Collector Current	T _C =80°C	40	A
		T _C =25°C	80	A
I _{CM}	Peak Collector Current Repetitive	T _J =150°C	80	A
t _{sc}	Short Circuit Withstand Time		>10	μs
P _D	Maximum Power Dissipation (IGBT)	T _C =25°C	255	W
		T _{Jmax} =150°C		



Electrical Characteristics of IGBT ($T_C=25^\circ\text{C}$ unless otherwise specified)

Static Characteristics

Symbol	Description	Conditions	Min.	Typ.	Max.	Units
$V_{GE(th)}$	Gate-Emitter Threshold Voltage	$I_C=1\text{mA}$, $V_{CE}=V_{GE}$, $T_J=25^\circ\text{C}$	5.00	5.60	6.50	V
$V_{CE(sat)}$	Collector-Emitter Saturation Voltage	$I_C=40\text{A}$, $V_{GE}=15\text{V}$	$T_J=25^\circ\text{C}$	2.00	2.30	V
			$T_J=125^\circ\text{C}$	2.30		V
			$T_J=150^\circ\text{C}$	2.40		V
I_{CES}	Collector-Emitter Leakage Current	$V_{GE}=0\text{V}$, $V_{CE}=V_{CES}$, $T_J=25^\circ\text{C}$			1	mA
I_{GES}	Gate-Emitter Leakage Current	$V_{GE}=\pm 20\text{V}$, $V_{CE}=0\text{V}$, $T_J=25^\circ\text{C}$			200	nA
C_{ies}	Input Capacitance	$V_{CE}=25\text{V}$, $V_{GE}=0\text{V}$, $f=100\text{kHz}$, $T_J=25^\circ\text{C}$		3.45		nF
C_{oes}	Output Capacitance			0.51		nF
C_{res}	Reverse Transfer Capacitance			0.04		nF

Switching Characteristics

$t_{d(on)}$	Turn-on Delay Time	$V_{CC}=600\text{V}$, $I_C=40\text{A}$, $R_{Gon}=30\Omega$, $V_{GE}=\pm 15\text{V}$, Inductive Load	$T_J=25^\circ\text{C}$	136		ns	
			$T_J=125^\circ\text{C}$	132			
			$T_J=150^\circ\text{C}$	147			
t_r	Rise Time		$T_J=25^\circ\text{C}$	74		ns	
			$T_J=125^\circ\text{C}$	74			
			$T_J=150^\circ\text{C}$	74			
$t_{d(off)}$	Turn-off Delay Time		$V_{CC}=600\text{V}$, $I_C=40\text{A}$, $R_{Goff}=30\Omega$, $V_{GE}=\pm 15\text{V}$, Inductive Load	$T_J=25^\circ\text{C}$	190		ns
				$T_J=125^\circ\text{C}$	196		
				$T_J=150^\circ\text{C}$	219		
t_f	Fall Time	$T_J=25^\circ\text{C}$		219		ns	
		$T_J=125^\circ\text{C}$		427			
		$T_J=150^\circ\text{C}$		484			
E_{on}	Turn-on Switching Loss	$V_{CC}=600\text{V}$, $I_C=40\text{A}$, $R_{Gon}=30\Omega$, $V_{GE}=\pm 15\text{V}$, $di/dt=490\text{A}/\mu\text{s}$ ($T_J=125^\circ\text{C}$), Inductive Load		$T_J=25^\circ\text{C}$	4.06		mJ
				$T_J=125^\circ\text{C}$	5.19		
				$T_J=150^\circ\text{C}$	5.55		



E _{off}	Turn-off Switching Loss	V _{CC} =600V, I _C =40A, R _{Goff} =30Ω, V _{GE} =±15V, du/dt=3440A/μs(T _J =125°C), Inductive Load	T _J =25°C	1.99	mJ
			T _J =125°C	3.42	
			T _J =150°C	3.85	
Q _g	Total Gate Charge	V _{GE} =+15V...-15V	T _J =25°C	460	nC
RBSOA	Reverse Bias Safe Operation Area	I _C =80A, V _{CC} =1050V, V _p =1200V, R _{Goff} =30Ω, V _{GE} =+15V to 0V, T _J =150°C	Trapezoid		
I _{SC}	V _{CC} =600V, V _{GE} =±15V, R _G =51Ω, t _p =10μs, T _J =125°C			128	A
R _{θJC}	IGBT Thermal Resistance: Junction-To-Case (per IGBT)			0.490	°C/W

Maximum Rated Values of Diode (T_C=25°C unless otherwise specified)

V _{RRM}	Repetitive Peak Reverse Voltage	1200	V
I _F	Diode Continuous Forward Current	40	A
I _{FM}	Diode Maximum Forward Current	80	A

Electrical Characteristics of Diode (T_C=25°C unless otherwise specified)

Symbol	Description	Conditions	Min.	Typ.	Max.	Units
V _{FM}	Forward Voltage	I _F =40A	T _J =25°C	1.80	2.20	V
			T _J =125°C	2.00		
			T _J =150°C	2.00		
t _{rr}	Reverse Recovery Time		T _J =25°C	297		ns
			T _J =125°C	586		
			T _J =150°C	611		
I _{rr}	Peak Reverse Recovery Current	I _F =40A, -di _F /dt=750A/μs(T _J =150°C), V _R =600V, V _{GE} =-15V	T _J =25°C	29.4		A
			T _J =125°C	36.2		
			T _J =150°C	37.5		
Q _{rr}	Reverse Recovery Charge		T _J =25°C	4.34		μC
			T _J =125°C	8.04		
			T _J =150°C	8.93		



E _{rec}	Reverse Recovery Energy	I _F =40A, -diF/dt=750A/μs(T _J =150°C), V _R =600V, V _{GE} =-15V	T _J =25°C	1.51	mJ
			T _J =125°C	3.02	
			T _J =150°C	3.40	
R _{θJC}	Diode Thermal Resistance: Junction-To-Case (per Diode)			0.682	°C/W

Internal NTC-Thermistor Characteristics

Symbol	Description		Min.	Typ.	Max.	Units.
R ₂₅	Rated Resistance	T _C =25°C		5		kΩ
ΔR/R	Deviation of R ₁₀₀	T _C =100°C, R ₁₀₀ =481Ω	-5		5	%
P ₂₅	Power Dissipation	T _C =25°C			10	mW
B _{25/50}	B-Value	$R_2=R_{25} \exp[B_{25/50}(1/T_2-1/(298.15K))]$		3380		K
B _{25/80}	B-Value	$R_2=R_{25} \exp[B_{25/80}(1/T_2-1/(298.15K))]$		3440		K
B _{25/100}	B-Value	$R_2=R_{25} \exp[B_{25/100}(1/T_2-1/(298.15K))]$		3545		K

Module

Symbol	Description		Min.	Typ.	Max.	Units.
V _{iso}	Isolation Voltage (All Terminals Shorted)	RMS, f=50Hz, 30s	4500			V
L _{sCE}	Stray Inductance Module			19		nH
T _J	Maximum Junction Temperature				150	°C
T _{JOP}	Maximum Operating Junction Temperature Range		-40		+150	°C
T _{stg}	Storage Temperature		-40		+125	°C
CTI	Comparative Tracking Index		200			
R _{θCS}	Case-To-Sink Thermally (Conductive Grease Applied)				0.03	°C/W
M	Mounting Torque for Module Mounting	Screw M5--Mounting according to valid application note	3.0		5.0	N·m
G	Weight			190		g



Ordering Information Table

Device code

G	T	40	FF	120	T5	H
①	②	③	④	⑤	⑥	⑦

- ① - IGBT Module
- ② - Trench, Low Switching Losses IGBT
- ③ - Rated Current (40=40A)
- ④ - Circuit Configuration: FF (Full Bridge)
- ⑤ - Rated Voltage (120=1200V)
- ⑥ - Package Type
- ⑦ - Test Level (Pass the Important Reliability Test-Industrial Grade)

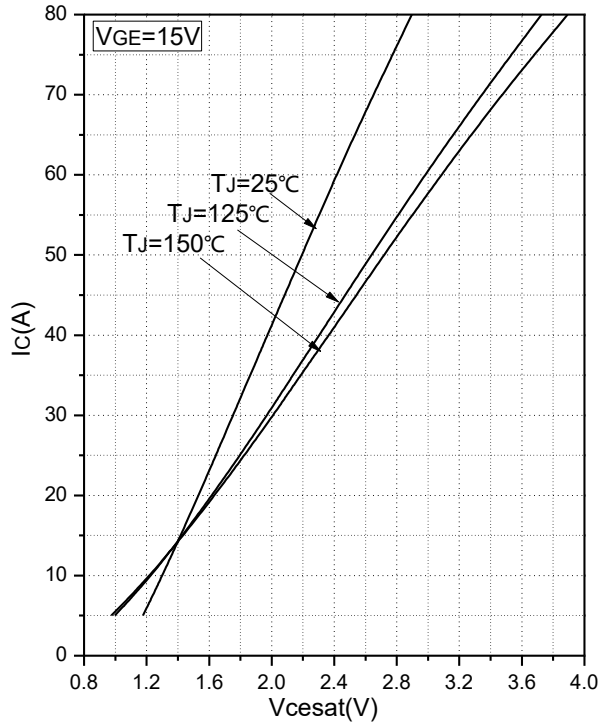


Fig.1 Typical Saturation Voltage Characteristics

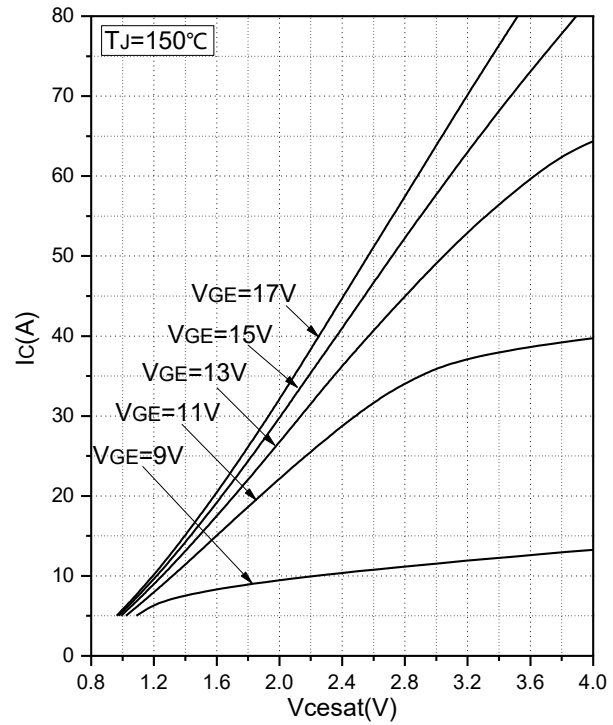


Fig.2 Typical Output Characteristics

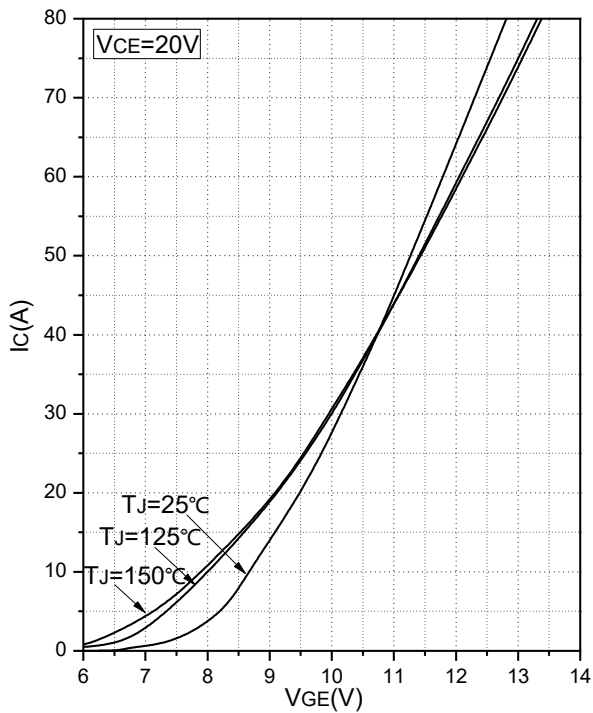


Fig.3 Transfer Characteristic

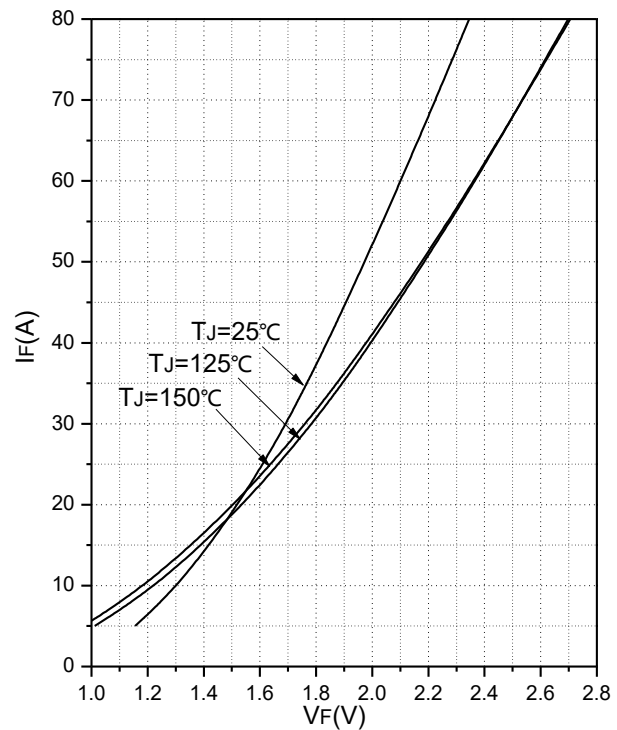


Fig.4 Forward Characteristics of Diode

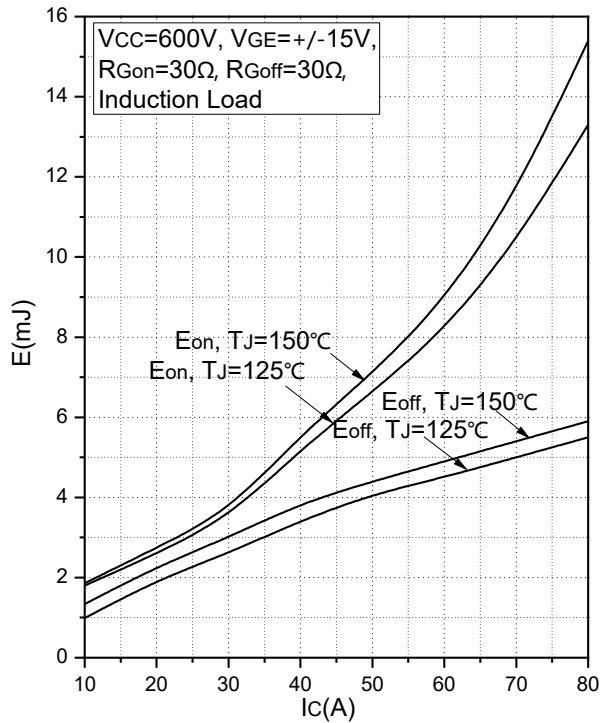


Fig.5 Typical Switching Loss vs. Collector Current

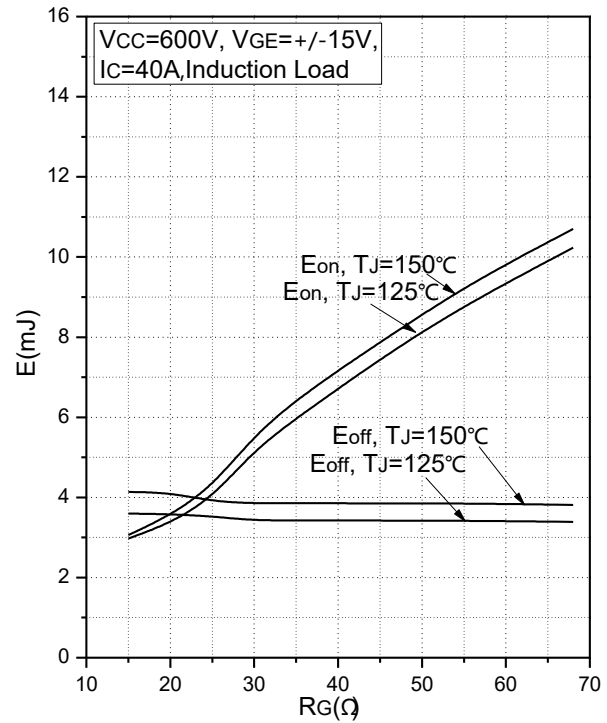


Fig.6 Typical Switching Loss vs. Gate Resistance

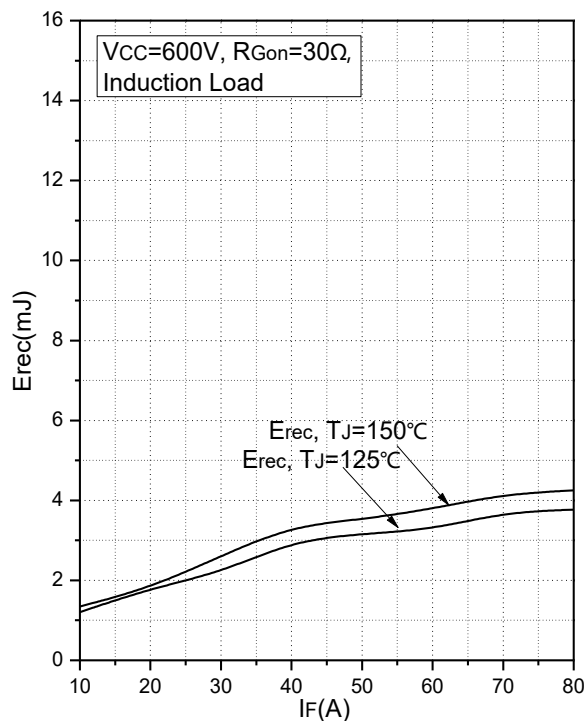


Fig.7 Typical Switching Loss vs. Forward Current

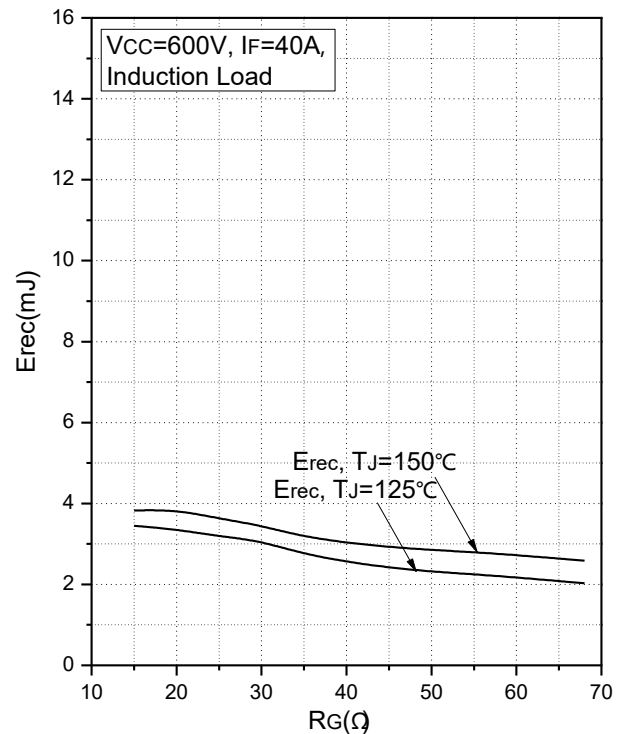


Fig.8 Typical Switching Loss vs. Gate Resistance

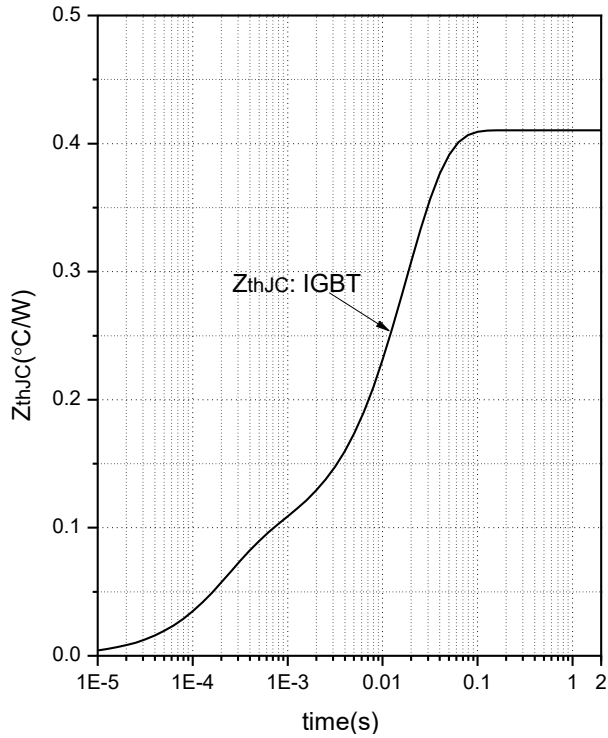


Fig.9 Transient Thermal Impedance (IGBT)

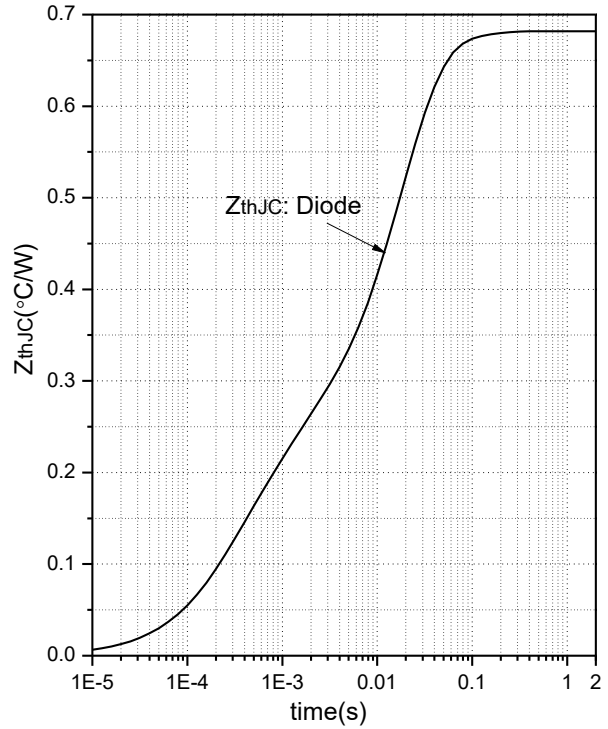


Fig.10 Transient Thermal Impedance (Diode)

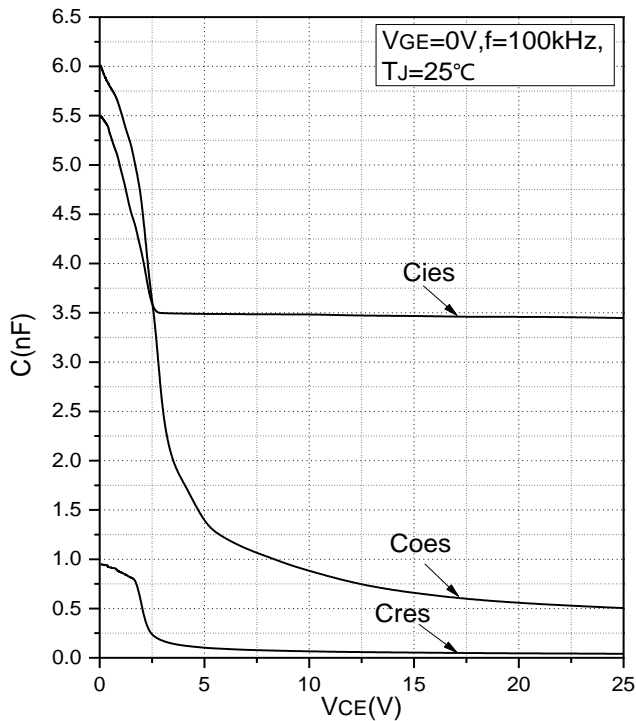


Fig.11 Capacitance Characteristics

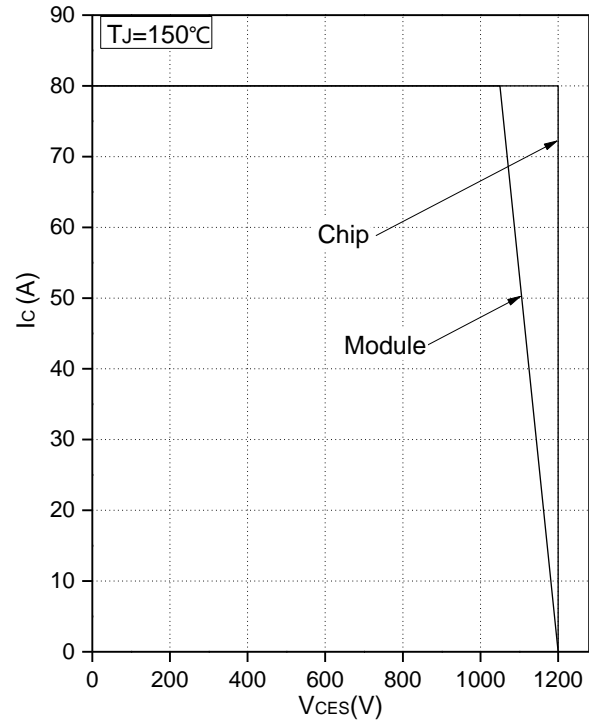


Fig.12 Reverse Bias Safe Operation Area (RBSOA)

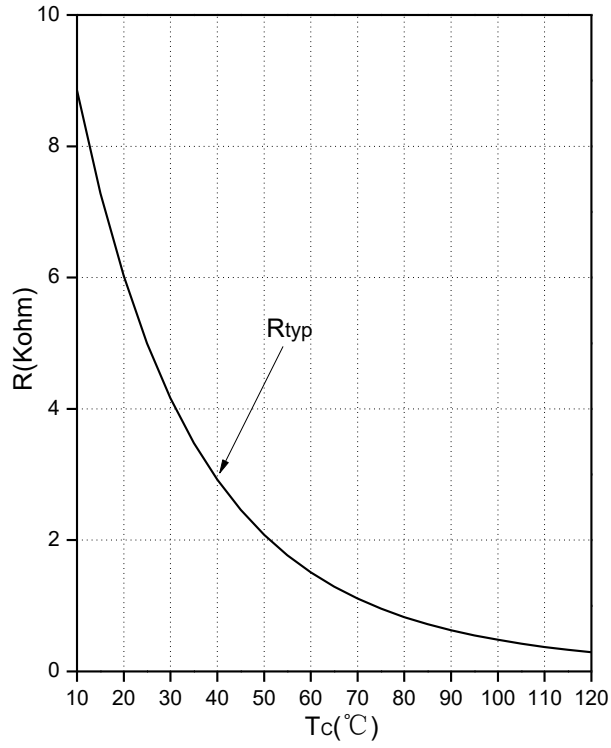
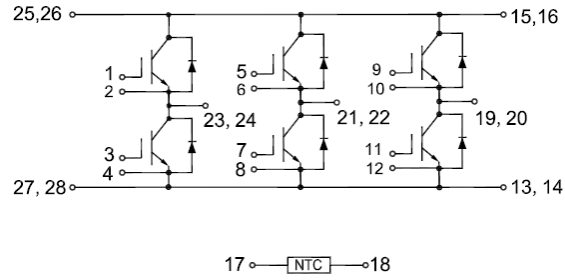


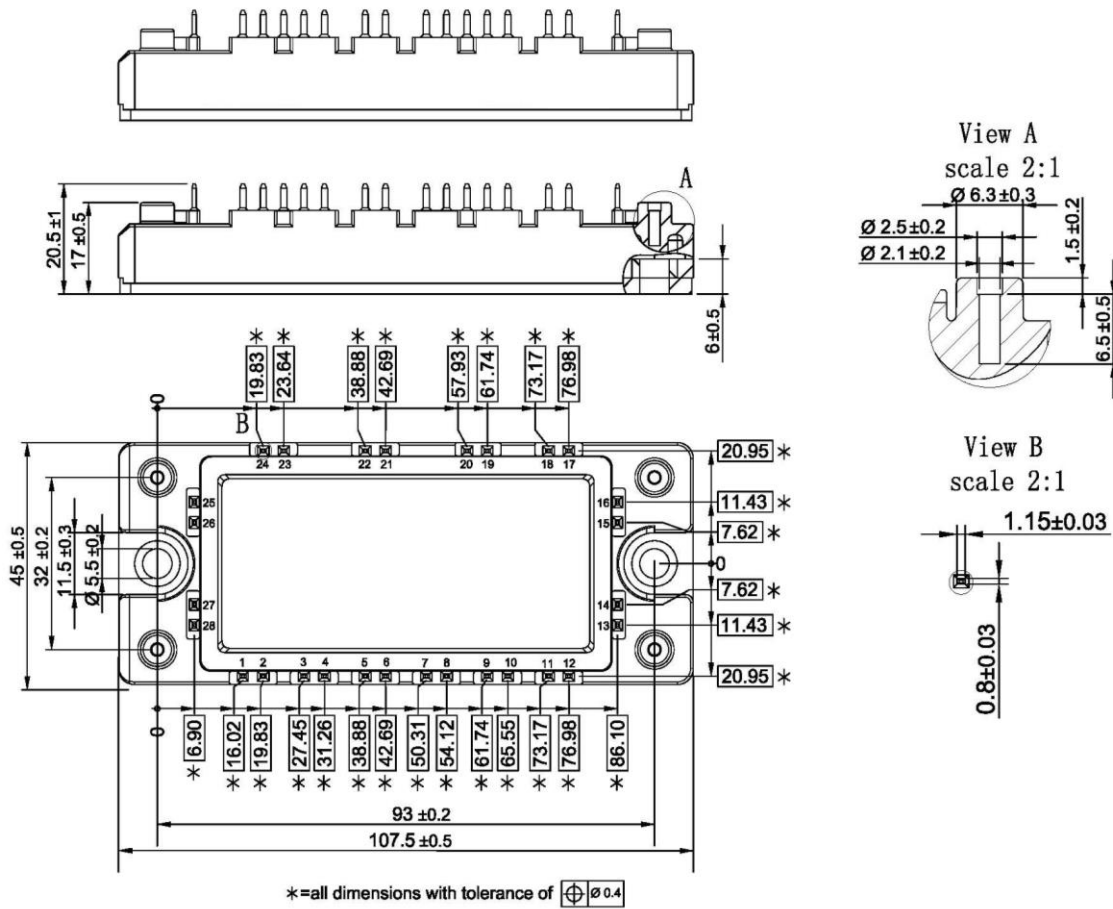
Fig.13 NTC Temperature Characteristics



Internal Circuit:



Package Outline (Unit: mm):





Date	Revision	Notes
08/21/2023	A	Final Version

Announcement

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